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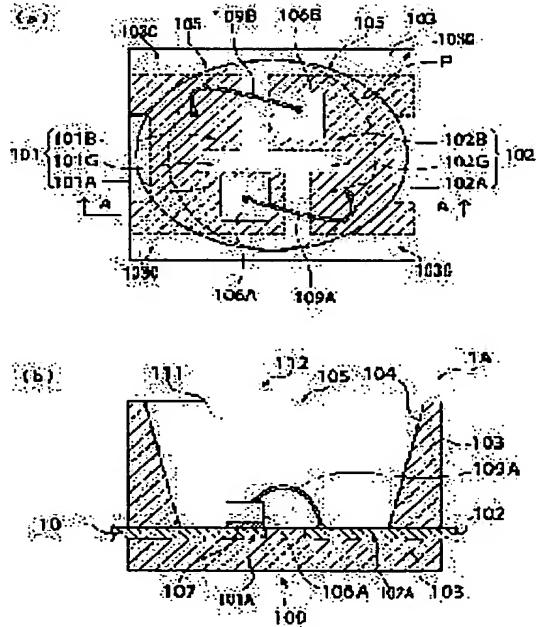
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(54) LIGHT EMITTING DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a light emitting device having a semiconductor light emitting element sealed with a resin which improves the reliability and the long stability and allows a plurality of chips to be compactly mounted.

SOLUTION: The opening is formed in an approximately elliptical or elongated circular shape to allow a plurality of chips to be efficiently laid within a limited space. A notch is formed between a wire-bonding region and a chip mounting region to avoid squeeze-out of adhesives, thereby solving bonding failures.



LEGAL STATUS

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